# Seong-Jae Jeon

List of Publications by Year
in descending order

Source: https://exaly.com/author-pdf/11896437/publications.pdf

Version: 2024-02-01

| 11 | 159 | 8 | 9 |
| --- | --- | --- | --- |
| papers | citations | h-index | g-index |
| | | 1163117 | 1474206 |

| 11 | 11 | 11 | 216 |
| --- | --- | --- | --- |
| all docs | docs citations | times ranked | citing authors |

| # | Article | IF | Citations |
| --- | --- | --- | --- |
| 1 | Study on the contact resistance of various metals (Au, Ti, and Sb) on Biâ€“Te and Sbâ€“Te thermoelectric films. Japanese Journal of Applied Physics, 2016, 55, 06JE03. | 1.5 | 5 |
| 2 | Introduction to the Thin Film Thermoelectric Cooler Design Theories. Journal of the Korean Society for Precision Engineering, 2014, 31, 881-887. | 0.2 | 0 |
| 3 | Microstructure evolution of sputtered BiSbâ€“Te thermoelectric films during post-annealing and its effects on the thermoelectric properties. Journal of Alloys and Compounds, 2013, 553, 343-349. | 5.5 | 19 |
| 4 | Enhanced Electrical Potential of Thermoelectric Power Waves by Sb<sub>2</sub>Te<sub>3</sub>-Coated Multiwalled Carbon Nanotube Arrays. Journal of Physical Chemistry C, 2013, 117, 913-917. | 3.1 | 26 |
| 5 | A hybridized graphene carrier highway for enhanced thermoelectric power generation. Physical Chemistry Chemical Physics, 2012, 14, 13527. | 2.8 | 24 |
| 6 | A Study on Sputtered Bi-Te Thermoelectric Films with Various Compositions: Microstructure Evolution and the Effects on Thermoelectric and Electrical Properties. Journal of Electronic Materials, 2012, 41, 60-66. | 2.2 | 10 |
| 7 | A Study on the Breakdown Mechanism of an Electroless-Plated Ni(P) Diffusion Barrier for Cu/Sn/Cu 3D Interconnect Bonding Structures. Journal of Electronic Materials, 2012, 41, 109-114. | 2.2 | 12 |
| 8 | Microstructure Evolution of Sputtered Bi-Te Films during Post-Annealing: Phase Transformation and Its Effects on the Thermoelectric Properties. Journal of the Electrochemical Society, 2011, 158, H808. | 2.9 | 9 |
| 9 | A Study on the Bonding Process of Cu Bump/Sn/Cu Bump Bonding Structure for 3D Packaging Applications. Journal of the Electrochemical Society, 2010, 157, H420. | 2.9 | 29 |
| 10 | Mechanical reliability evaluation of Sn-37Pb solder joint using high speed lap-shear test. Microelectronic Engineering, 2008, 85, 1967-1970. | 2.4 | 25 |
| 11 | Mechanical Reliability Evaluation of Sn-37Pb/Cu and Sn-37Pb/ENIG Solder Joints by using High Speed Lap-shear Test. , 2008, , . | | 0 |